

# MTP2955V-VB Datasheet P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub>	-60	V		
$R_{DS(on)} V_{GS} = 10 V$	62	mΩ		
$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}$	74	mΩ		
I <sub>D</sub>	-40	Α		
Configuration	Single			

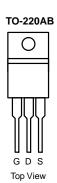
#### **FEATURES**

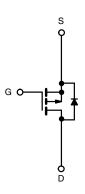
- Trench Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_C = 25$ °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	-40		
	T <sub>C</sub> = 100 °C		-30		
Pulsed Drain Current		I <sub>DM</sub>	- 90	Α	
Continuing Source Current (Diode Conduction)		I <sub>S</sub>	- 30		
Avalanche Current		I <sub>AS</sub>	- 28	1	
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	В	60 <sup>a</sup>	w	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2 <sup>b</sup>	] vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hungkian ka Amahiank	t ≤ 10 sec	R <sub>thJA</sub>	20	25		
Junction-to-Ambient <sup>b</sup>	Steady State		62	75	°C/W	
Junction-to-Case		R <sub>thJC</sub>	5	6		

#### Notes:

- a. See SOA curve for voltage derating.
- b. Surface Mounted on 1" x 1" FR-4 boad.



Parameter	Symbol	Test Conditions	Min	Typ <sup>a</sup>	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μΑ	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 150		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 10			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A		62			
D : 0	r	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 125 °C		80			
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 175 °C		110		mΩ	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2 A		74			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A		8		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			1300		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120			
Reverse Transfer Capacitance	C <sub>rss</sub>			90			
Total Gate Charge	$Q_g$			13			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8.4 \text{ A}$		2.3		nC	
Gate-Drain Charge	$Q_{gd}$			3.2			
Gate Resistance	$R_g$	f = 1 MHz		8.0		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			5	10		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, R_L = 3.57 \Omega$		14	25	20	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -8.4 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 2.5 \Omega$		15	25	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	]		7	12		
Source-Drain Diode Ratings and Cha	aracteristics	(T <sub>C</sub> = 25 °C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>			- 20		Α	
Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = -2 A, V <sub>GS</sub> = 0 V		- 0.9	- 1.3	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 9 A di/dt = 100 A/::2		50	80	ns	
Reverse Recovery Time	Q <sub>rr</sub>	I <sub>F</sub> = - 8 A, di/dt = 100 A/μs		80	120	nC	

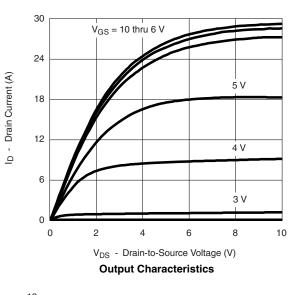
#### Notes:

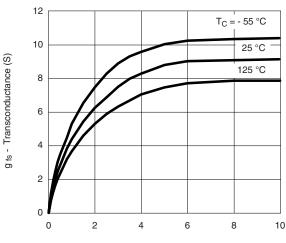
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

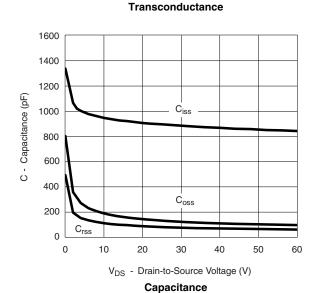


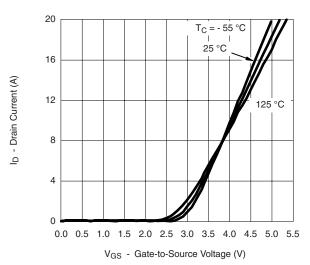
#### TYPICAL CHARACTERISTICS 25 °C unless noted

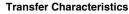


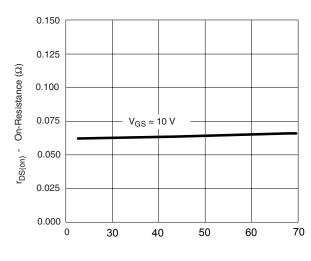


I<sub>D</sub> - Drain Current (A)

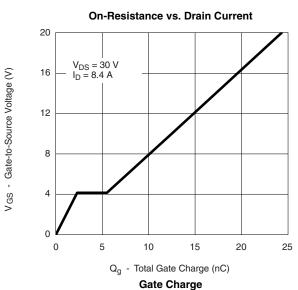








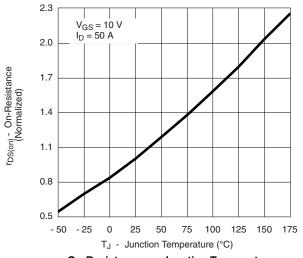
I<sub>D</sub> - Drain Current (A)



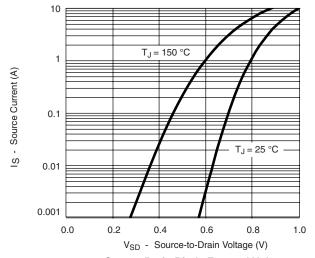
服务热线: 400-655-8788



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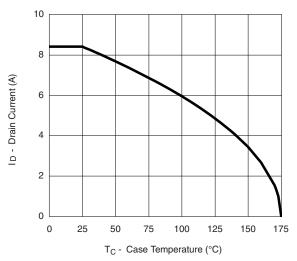


On-Resistance vs. Junction Temperature

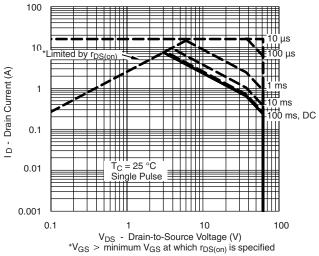


Source-Drain Diode Forward Voltage

#### THERMAL RATINGS



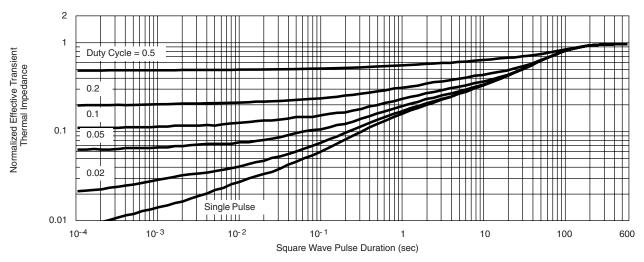
**Drain Current vs. Case Temperature** 



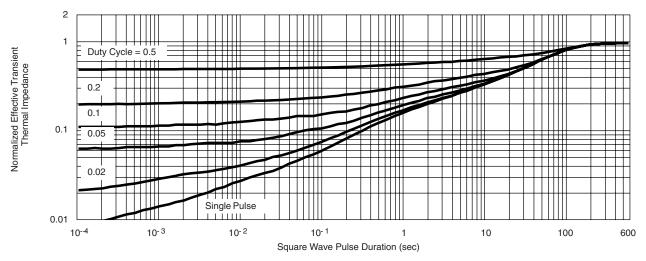
Safe Operating Area



#### THERMAL RATINGS



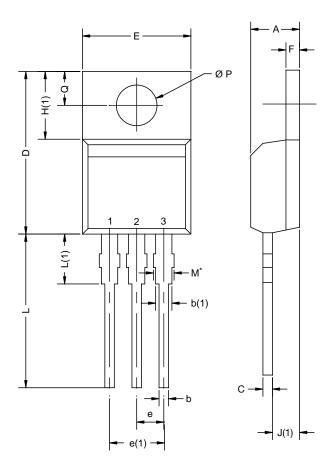
#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-220AB**



	MILLIM	IETERS	INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	4.25	4.65	0.167	0.183		
b	0.69	1.01	0.027	0.040		
b(1)	1.20	1.73	0.047	0.068		
С	0.36	0.61	0.014	0.024		
D	14.85	15.49	0.585	0.610		
Е	10.04	10.51	0.395	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.09	6.48	0.240	0.255		
J(1)	2.41	2.92	0.095	0.115		
L	13.35	14.02	0.526	0.552		
L(1)	3.32	3.82	0.131	0.150		
ØР	3.54	3.94	0.139	0.155		
Q	2.60	3.00	0.102	0.118		
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471						

#### Notes

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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